

Universita'  
di Padova



Istituto Nazionale  
Di Fisica Nucleare  
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# Single Event Effect Assessment and Radiation Monitor with a Ion Photon Emission Microscope

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Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company, for the United States Department of Energy under contract DE-AC04-94AL85000.

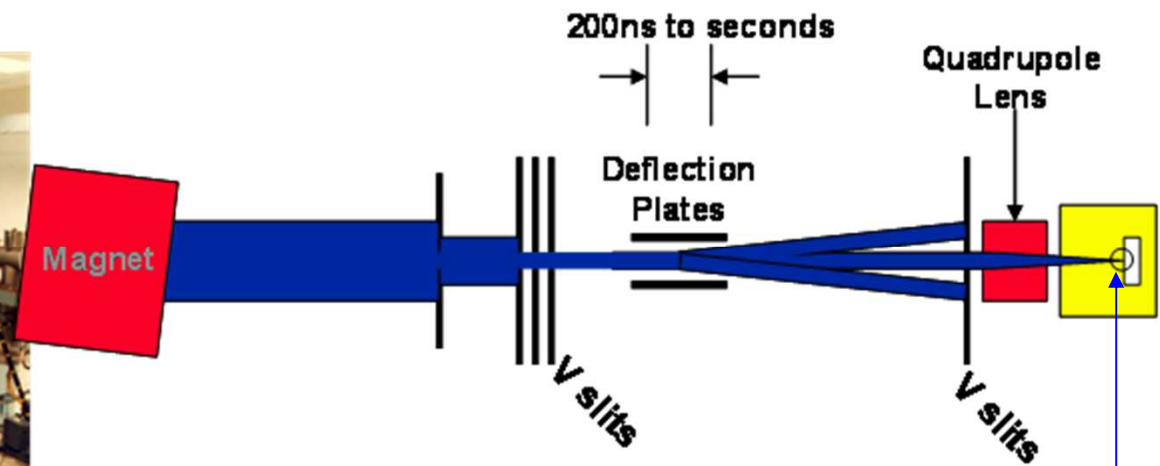
Work supported in part by the Italian "Istituto Nazionale di Fisica Nucleare" (INFN).



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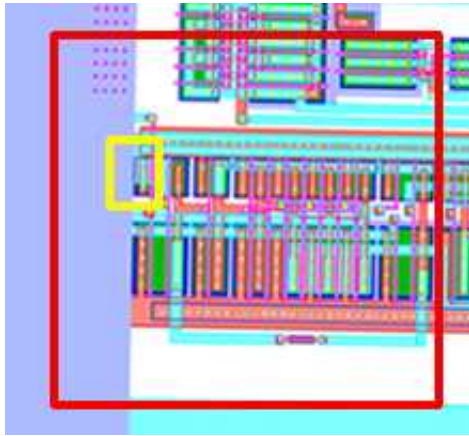
# Microscopy with Ion Beams

for assessing “local” failures (SEE) in a chip subjected to radiation and help improving the design of the same

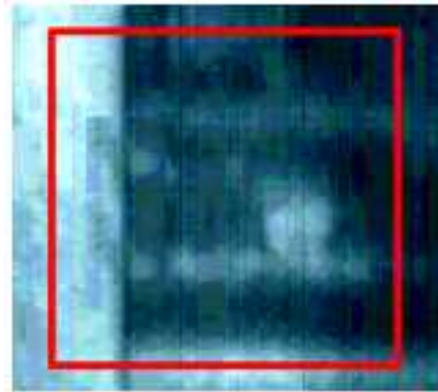


Low intensity beams of high energy ions are focused into a micro-region on a microchip

# SEE Imaging at Sandia $\mu$ one



GDSII Navigation

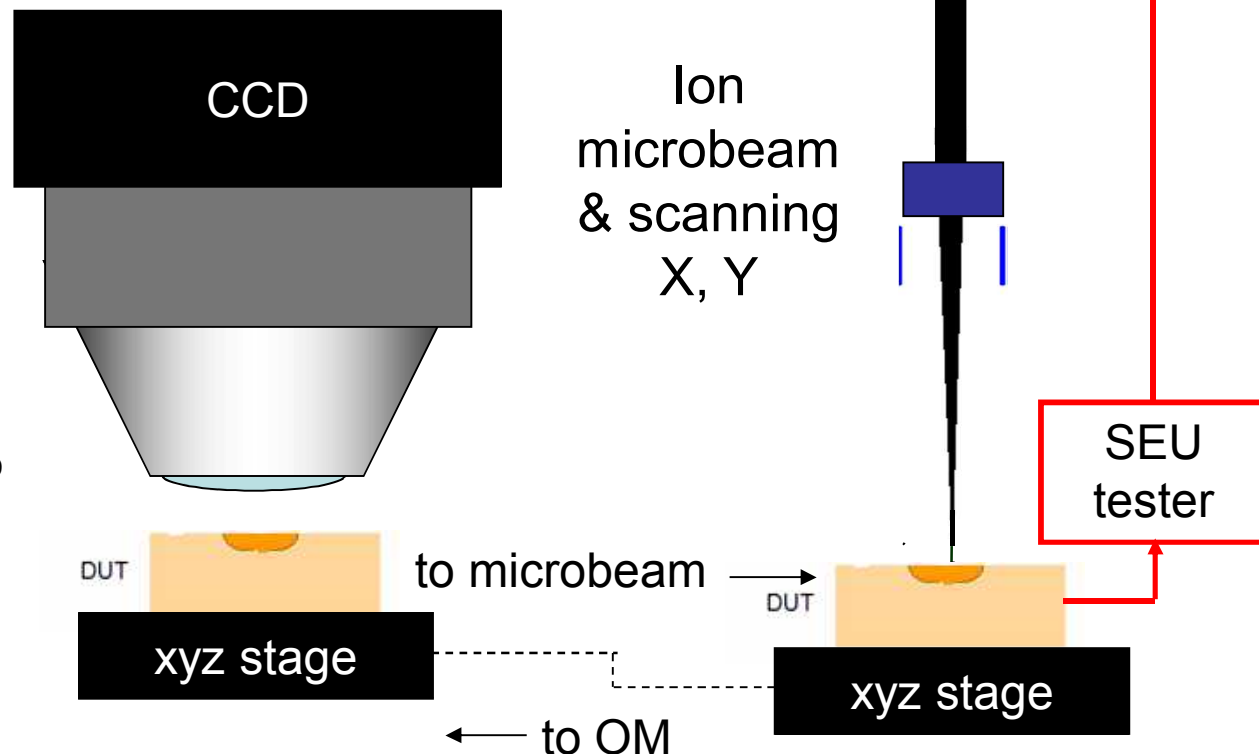


Optical Microscope OM

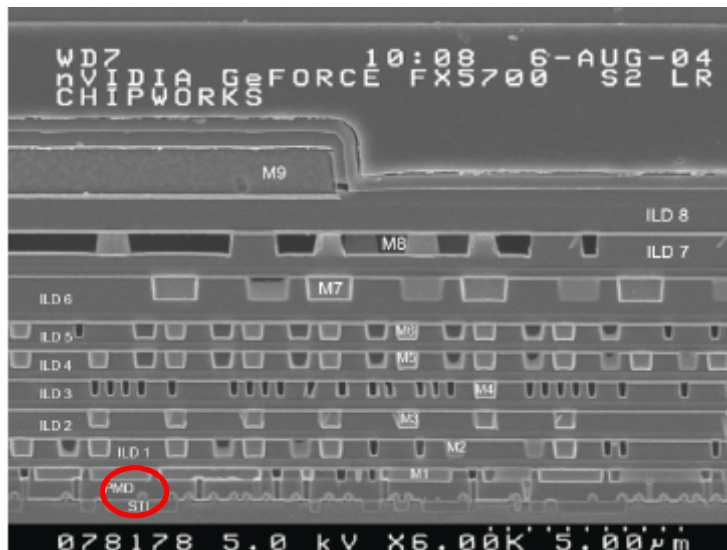


SEU map

1. GDSII or bmp files loaded
2. Optical Microscope - OM
  - IC brought into focus
  - IC landmarks found – positions tagged
  - GDSII calibrated to xyz stage
3. IC translated to the microbeam
  - Translation vector previously determined
  - Suspect components scanned to
  - Or whole IC scanned – SEE locations tagged
  - IBIC and SEE images taken
4. Position of SEEs overlaid on OM and GDSII
  - Rad sensitive parts identified



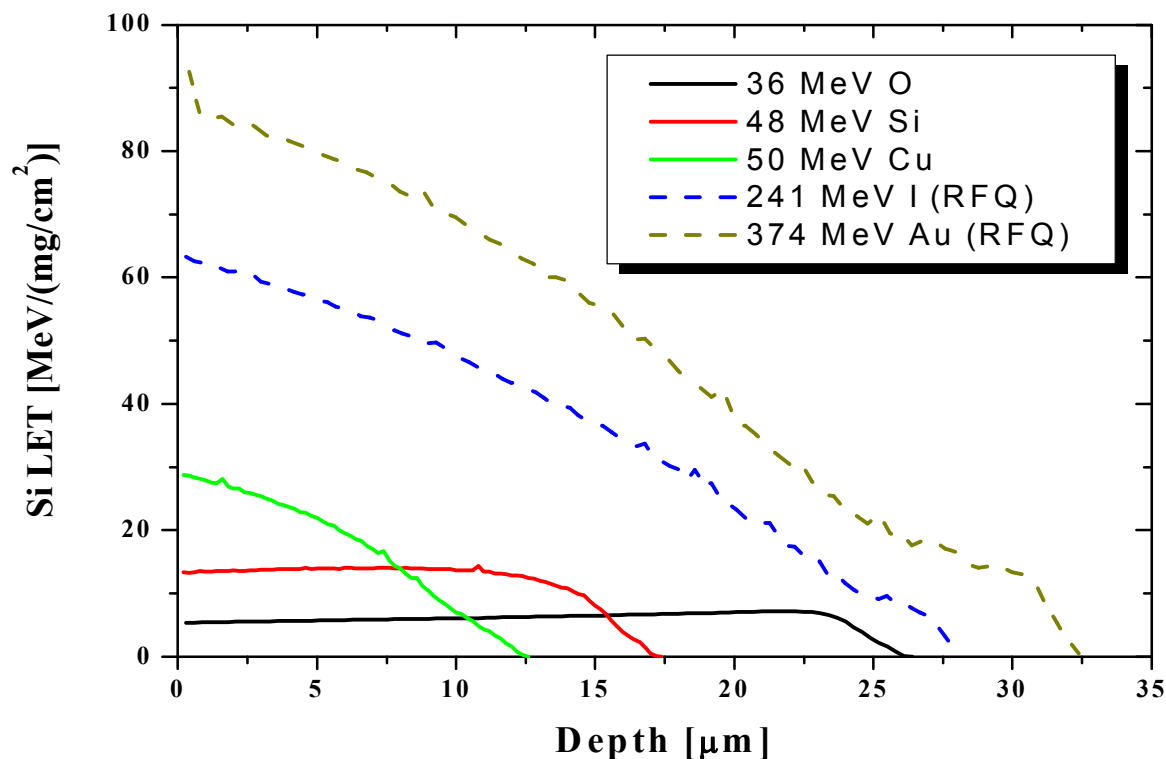
16  
 $\mu\text{m}$



## Modern ICs vs. our LET range.

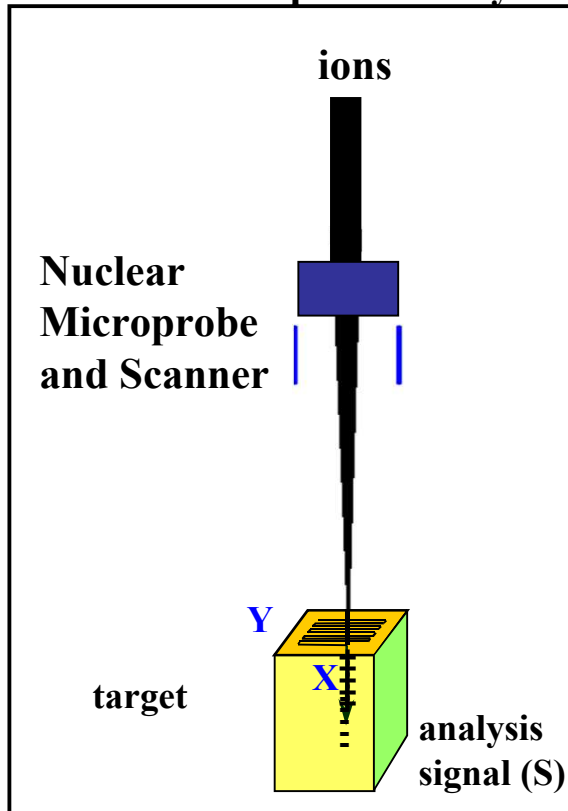
To explore SEE on chips with very thick metallization, interlevel dielectrics and passivation layers, one needs Cyclotron Energies (TAMU, Michigan State, or LBNL 88-inch Cycl. )

How to do Radiation Microscopy at such energies ??

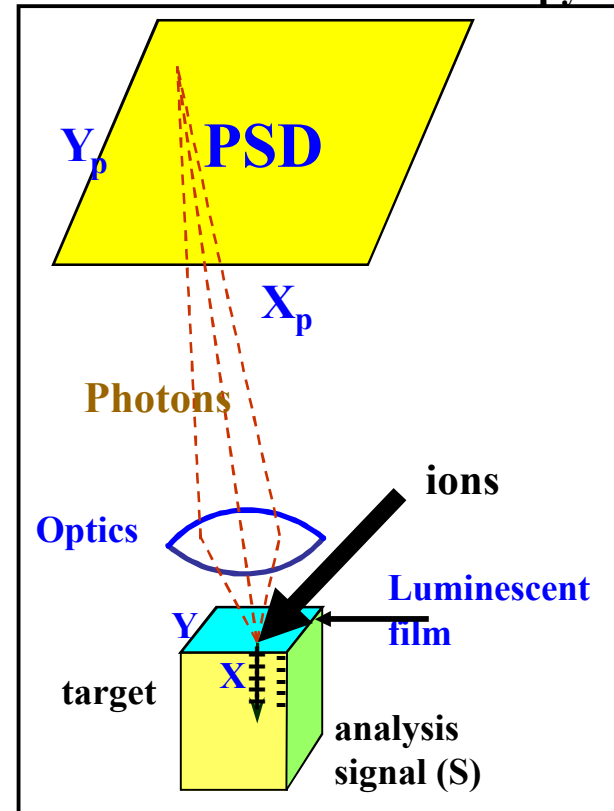


**Problem: High Energy Ions are very difficult to focus**  
**Solution: detect instead the impact point!**

**Nuclear Microprobe Analysis**



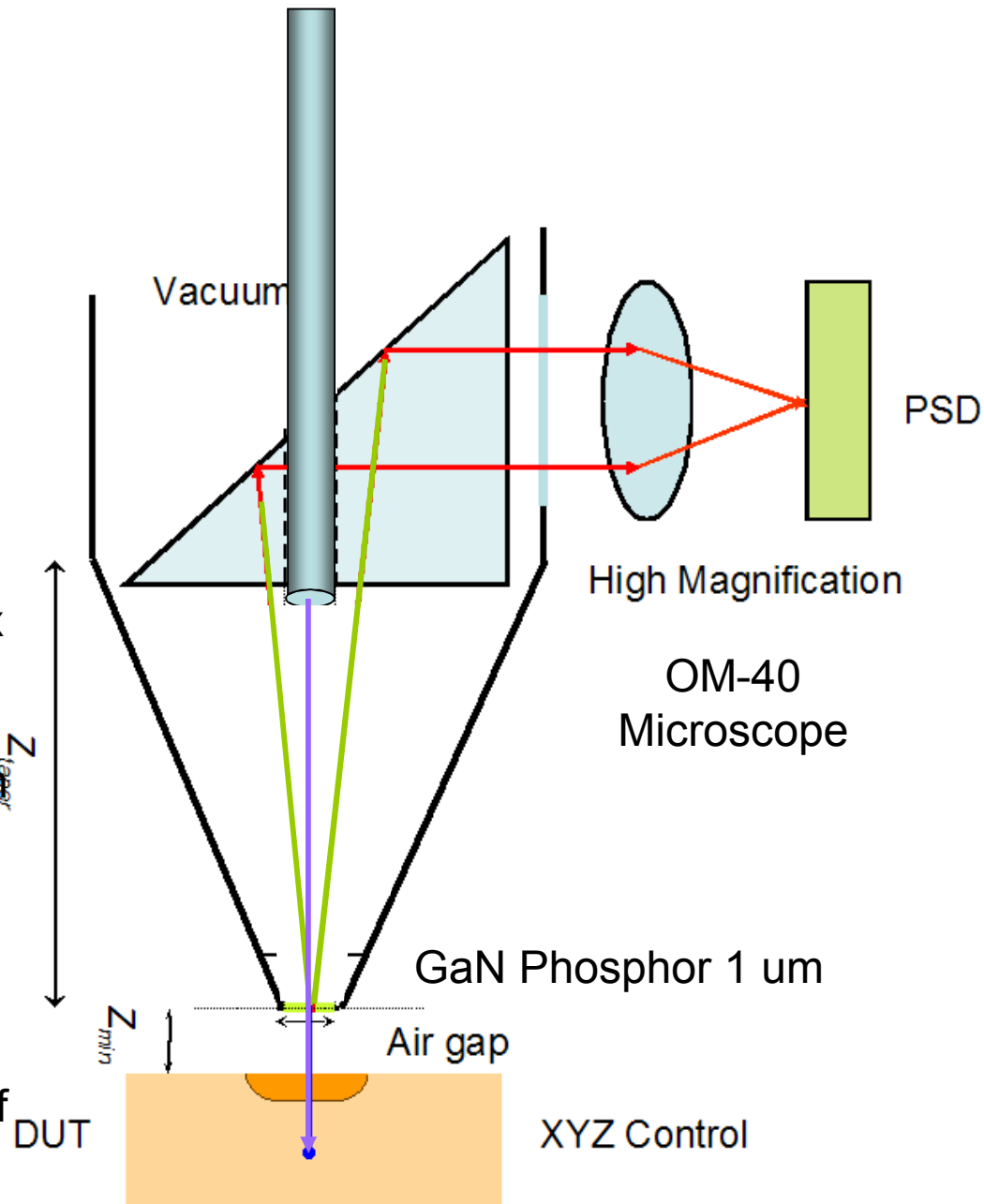
**Nuclear Emission Microscopy**



# Cyclotron IPEM

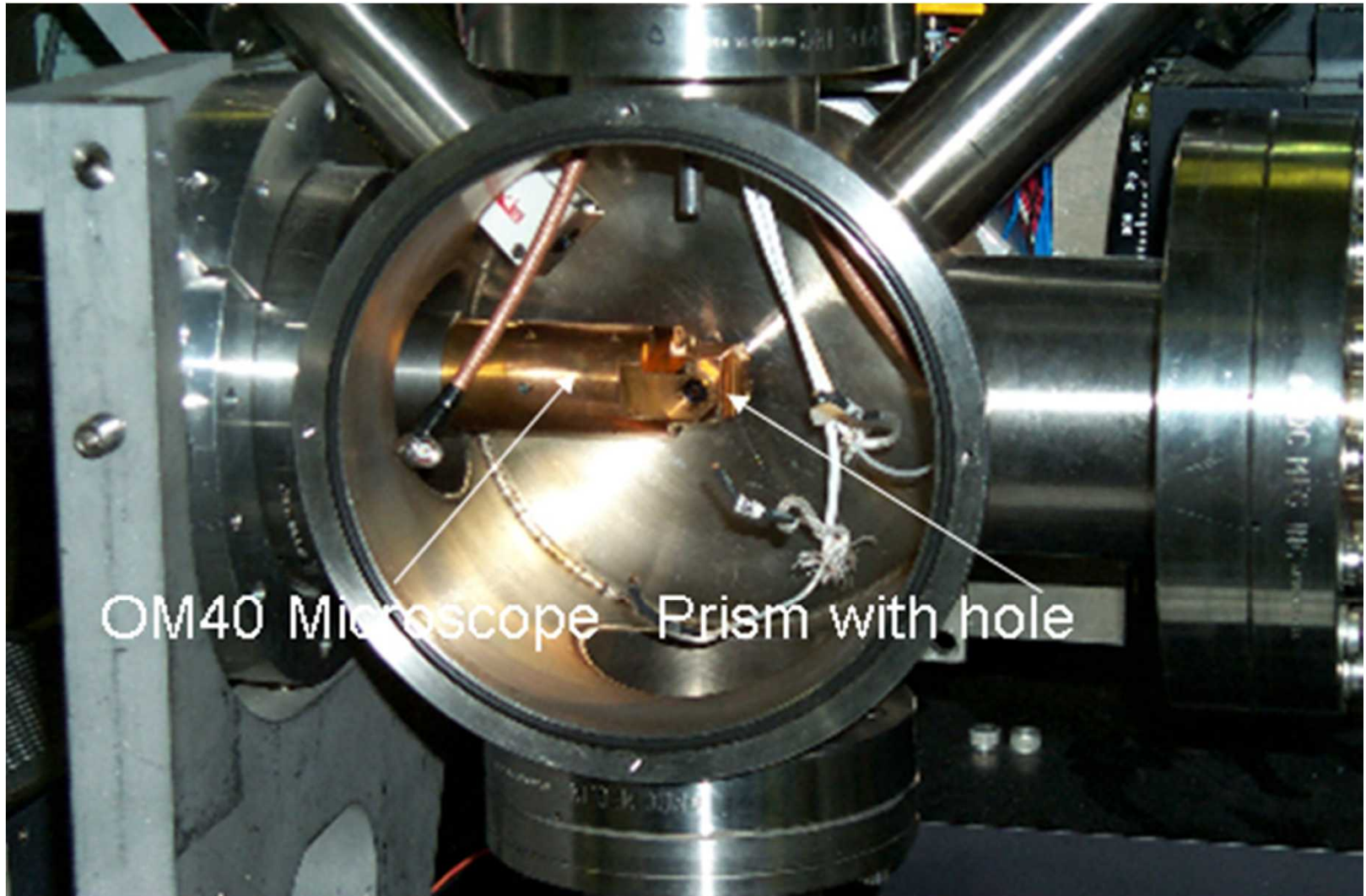
## A Radiation Microscope for SEE testing ( $> \text{GeV}$ )

1. Beam from Cyclotron exits nozzle thru  $1\mu\text{m}$  Al foil
2. Transmitted 6mm in air to  $1\mu\text{m}$  GaN phosphor blade
3. Air gap is  $< 100\mu\text{m}$
4. Angular scattering and beam divergence of  $5\text{mrad}$  means parallax angle of beam in air gap is  $10\text{mrad}$ .
5. Parallax and exit foil+airgap+GaN scattering effect on resolution is  $1\mu\text{m}$
6. Blooming to be  $< 1\mu\text{m}$
7. Net resolution of IPEM  $\sim 1\text{-}2\mu\text{m}$
8. XYZ stage calibrated to GDSII file
9. Computer navigation to IC components
10. REM data presented as overlays of optical, GDSII, and SEE images to quickly identify rad sensitive components.





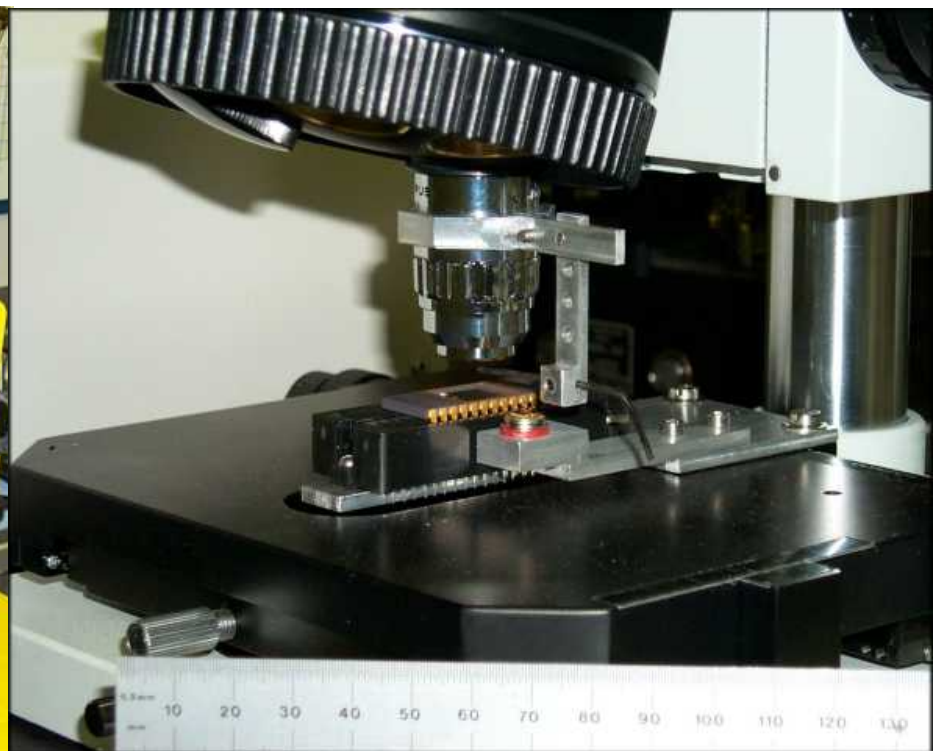
# Scattering Chamber and OM40 Microscope



The JEOL OM-40 microscope has a 1.5 mm hole for the beam crossing. The current system is in vacuum, but IPEM can be performed eXternally. Light is conveyed from the OM-40 to the PSD outside the chamber



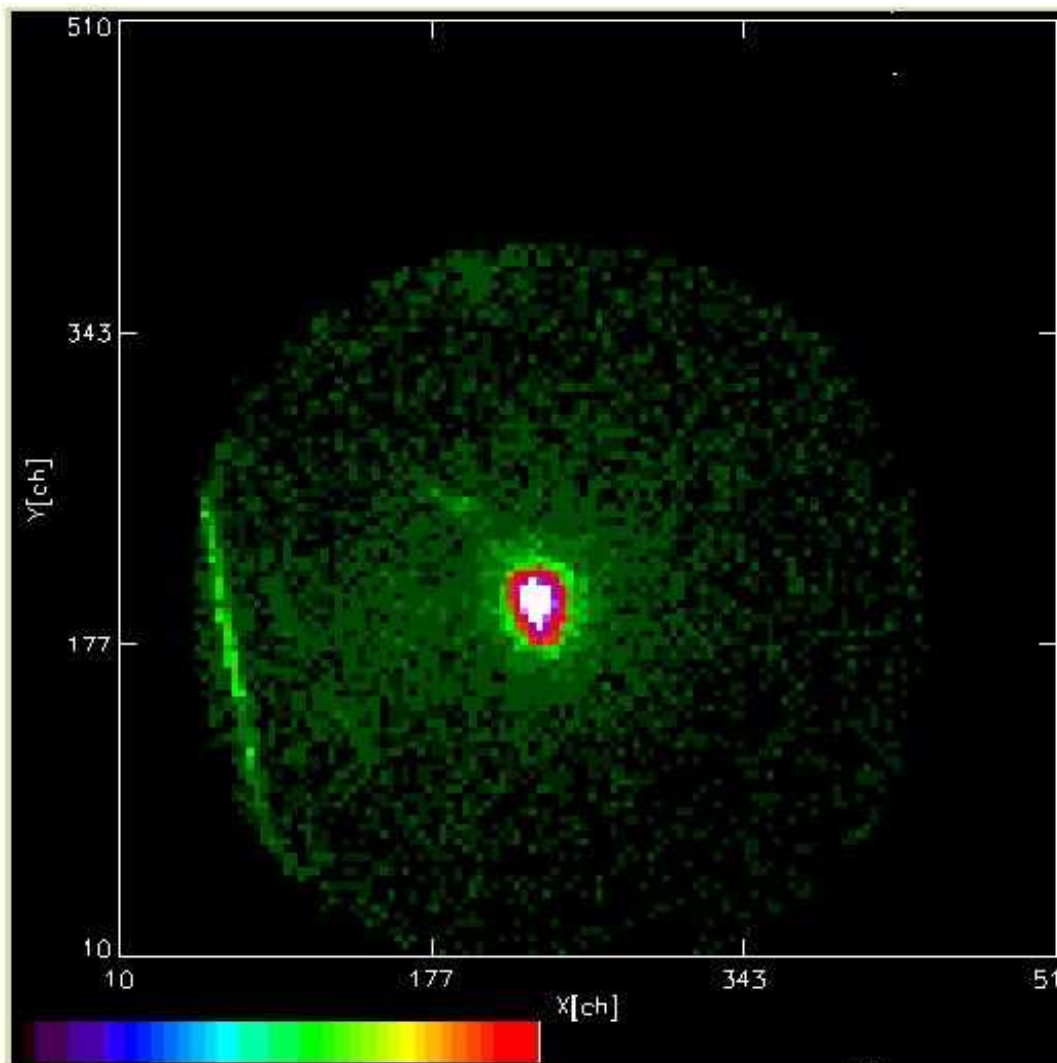
# ALPHA PARTICLE TABLE-TOP IPEM



**QUANTAR Mepsicon PSD**  
on top of the Microscope



## POINT SPREAD FUNCTION (C20 MeV)



SNL 6MV Tandem  
45° line Chamber

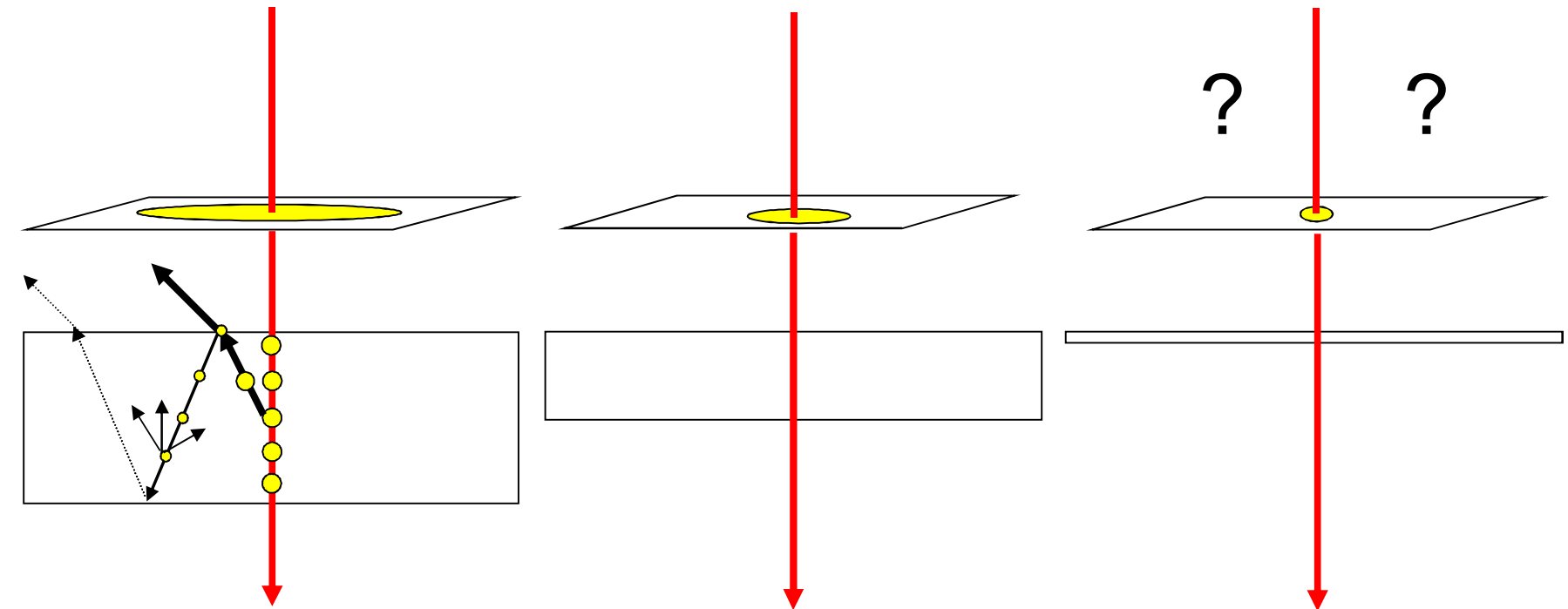
Focused microbeam  
With a spot size of 2-  
3  $\mu\text{m}$ , impinging a 10  
 $\mu\text{m}$  BC400 blade

**FWHM = 12  $\mu\text{m}$**   
**TP (Tail %)= 20%**

## Which Phosphor ?

To avoid the “blooming” the phosphor layer should be as thin as possible provided enough light is produced ->

**High yield Phosphors workable into thin films**



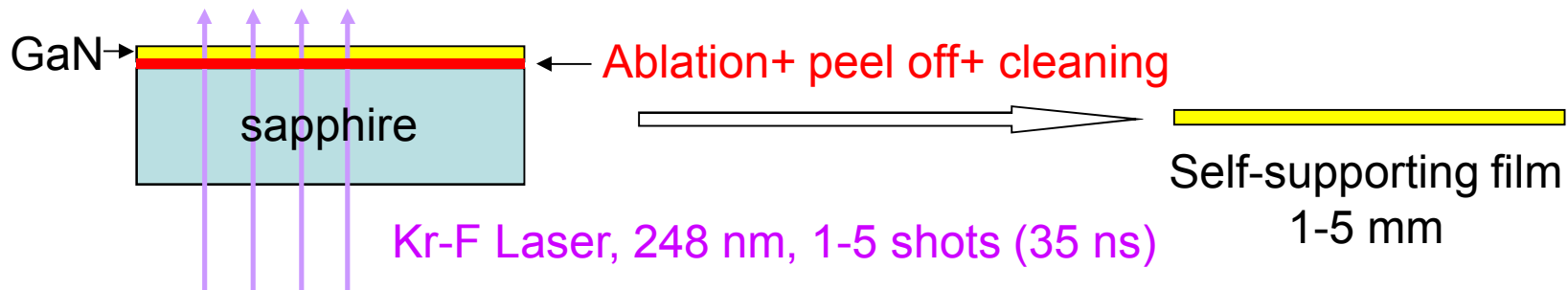
Bicron 400 (10  $\mu\text{m}$  thick)  
Resolution FWHM  $\sim 10 \mu\text{m}$

GaN (5  $\mu\text{m}$  thick)  
FWHM  $\sim 3\text{-}5 \mu\text{m}$

InGaN-QW (1  $\mu\text{m}$  thick)  
FWHM  $\sim 1 \mu\text{m}$

# GaN blades preparation

GaN films are routinely grown with MOCVD on sapphire at SNL. Since we needed freestanding foils we developed a method to turn these films to self-supporting foils using laser ablation to detach the films from their sapphire substrates. The films were grown on substrates polished on both sides to facilitate uniform transmission of the Kr-F laser light through the sapphire. Crystal Bond was used to glue the samples face down to a salt substrate to provide mechanical rigidity before and after ablation and to provide a measure of heat sinking. For some samples a holding grid such as a TEM ring was inserted in the glue interface at the front of the GaN layer. Samples were exposed to 1-5 shots of 248 nm, 34 ns laser light, with energy densities in the range of 800-1200 mJ/cm<sup>2</sup> over an area of ~4mm<sup>2</sup>. Adsorption of the laser light induces rapid thermal decomposition at the interface, producing Ga and N<sub>2</sub> gas and de-bonding the film from the sapphire. After exposure, the salt was dissolved away in water and the Crystal Bond removed with acetone. The resulting GaN films were cleaned in dilute HCl to remove residual Ga metal at the back interface. This method produced high quality self-supporting films down to 1 mm thickness and now it used to routinely produce these films.



# Evaluation of the phosphors' performance with the table-top IPEM

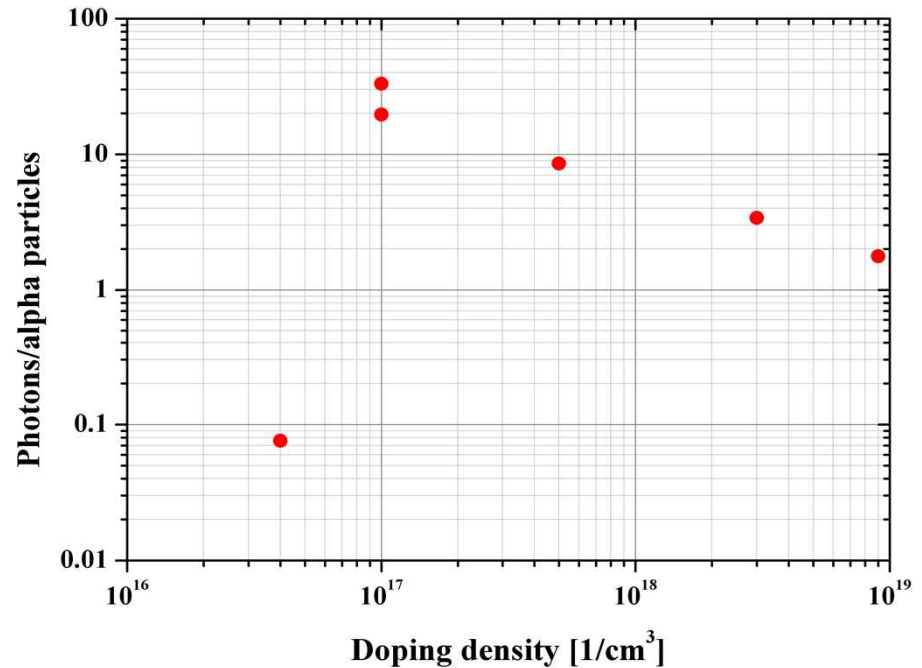
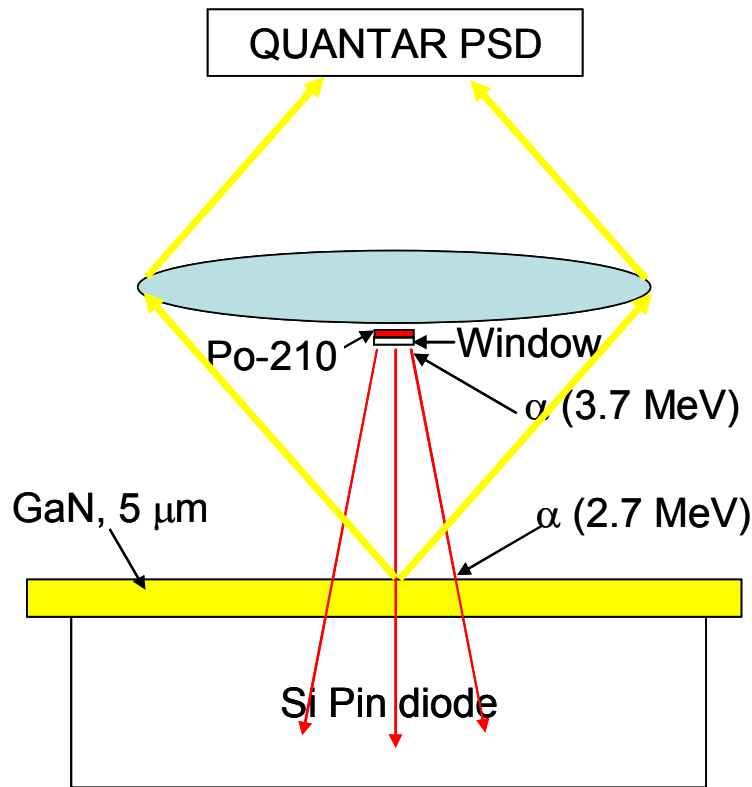
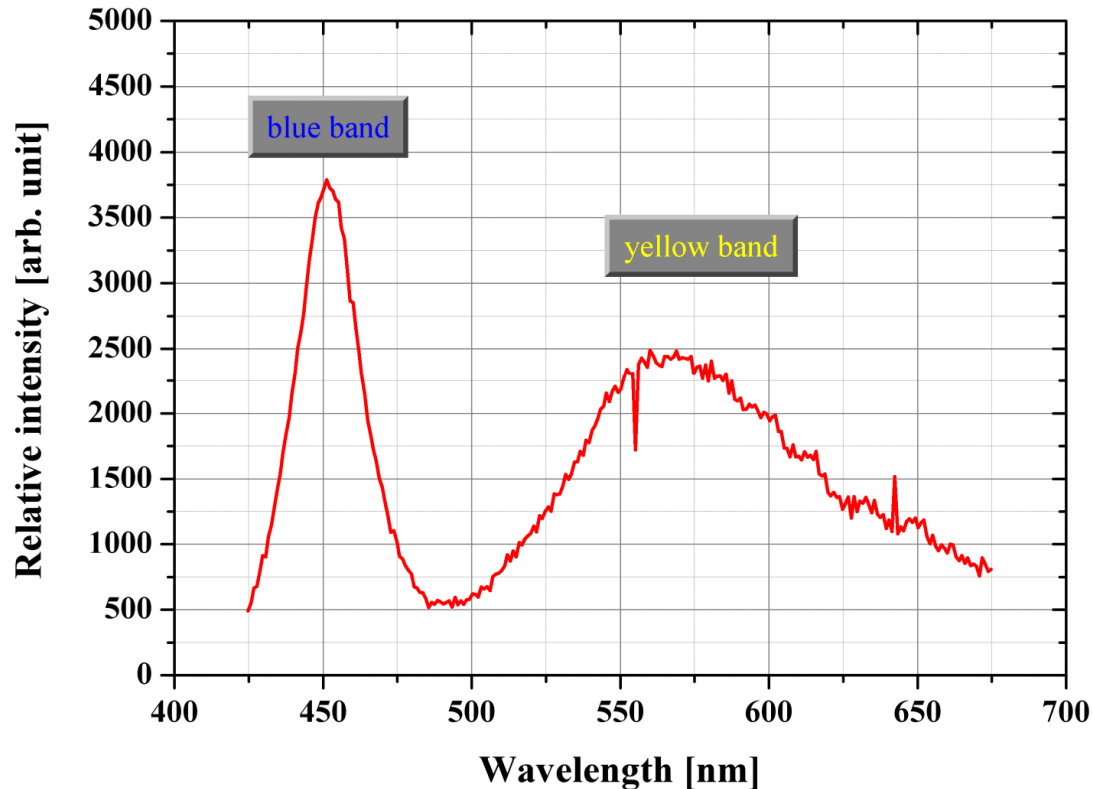


Figure 1

The p-type GaN has negligible visible ion-luminescence (IL) emission while the n-type GaN IL increases with decreasing doping level and peaks around  $10^{17} \text{ atoms/cm}^3$  then drops down steeply. We also found that the light lifetime has roughly an inverse behavior.

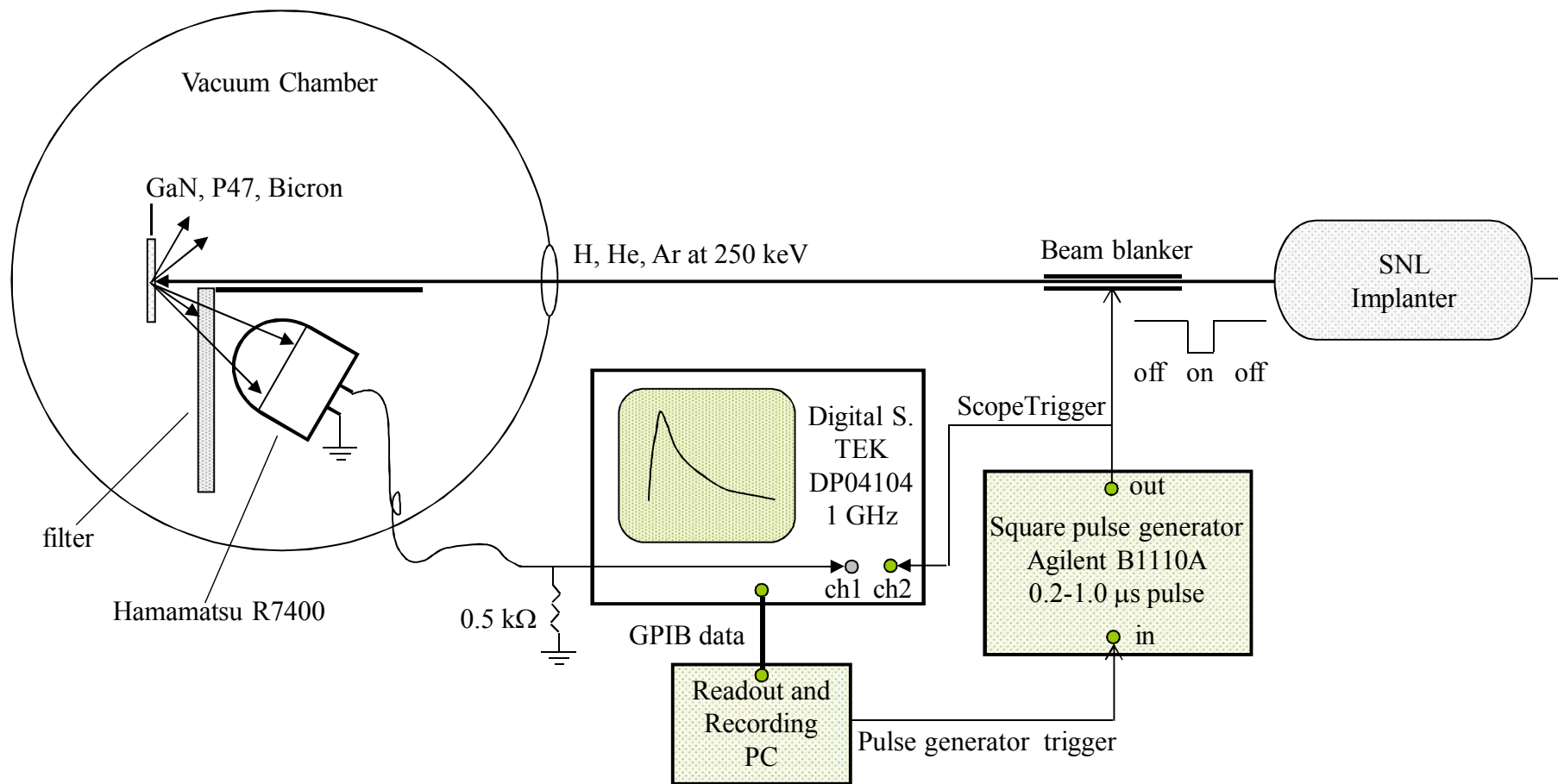
## GaN spectra



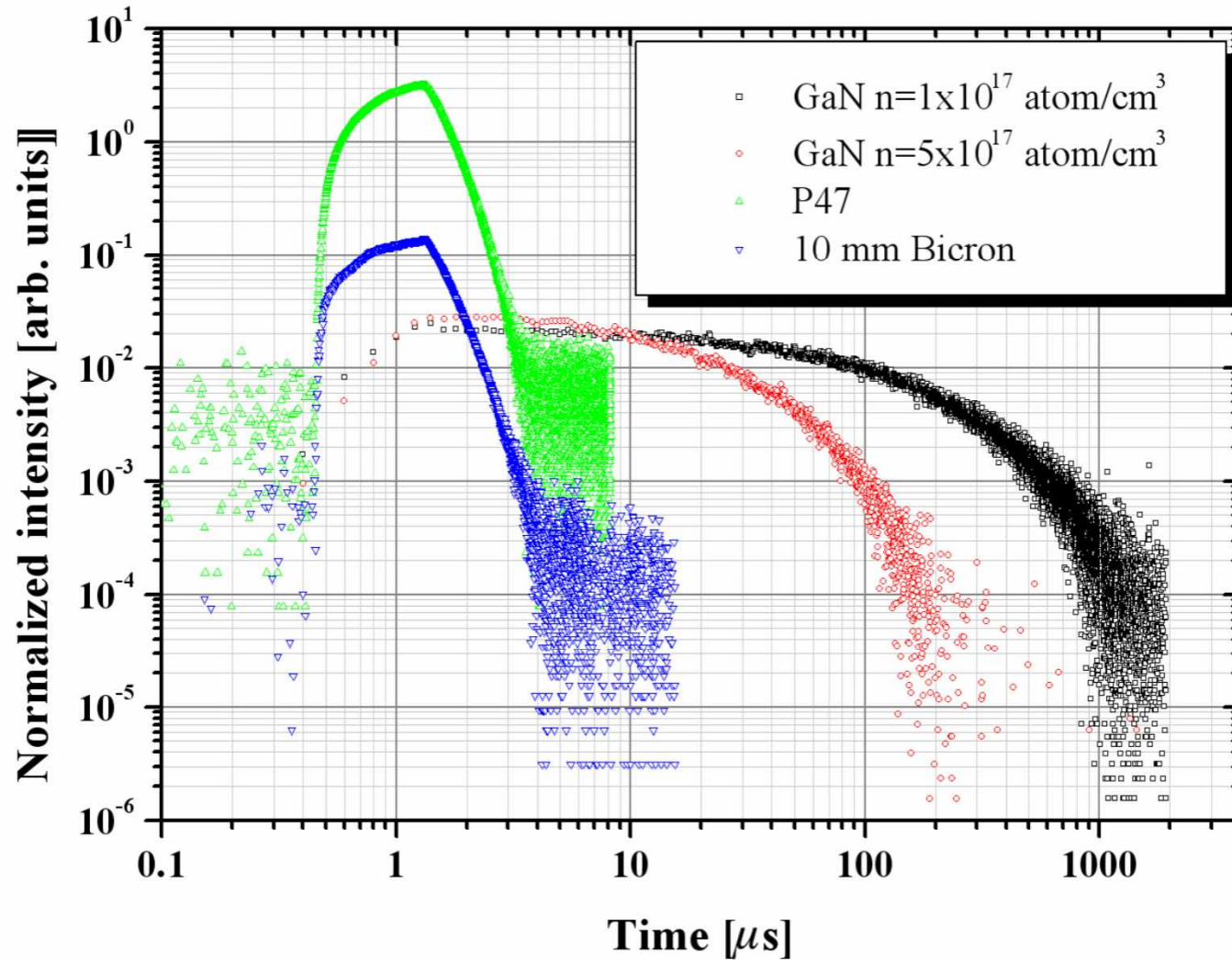
the n-type GaN and InGaN have emission bands centered at 360-UV (GaN), 450-blue (InGaN), and 560-yellow nm. In particular, the UV and blue bands, due to bandgap transitions, have a very short lifetime but reduced intensities. It is the yield of the yellow band that we found to change with the doping concentration (Figure 1) and that may become extremely high.



# Light Yield, Spectrum and Life Time measurements at the implanter



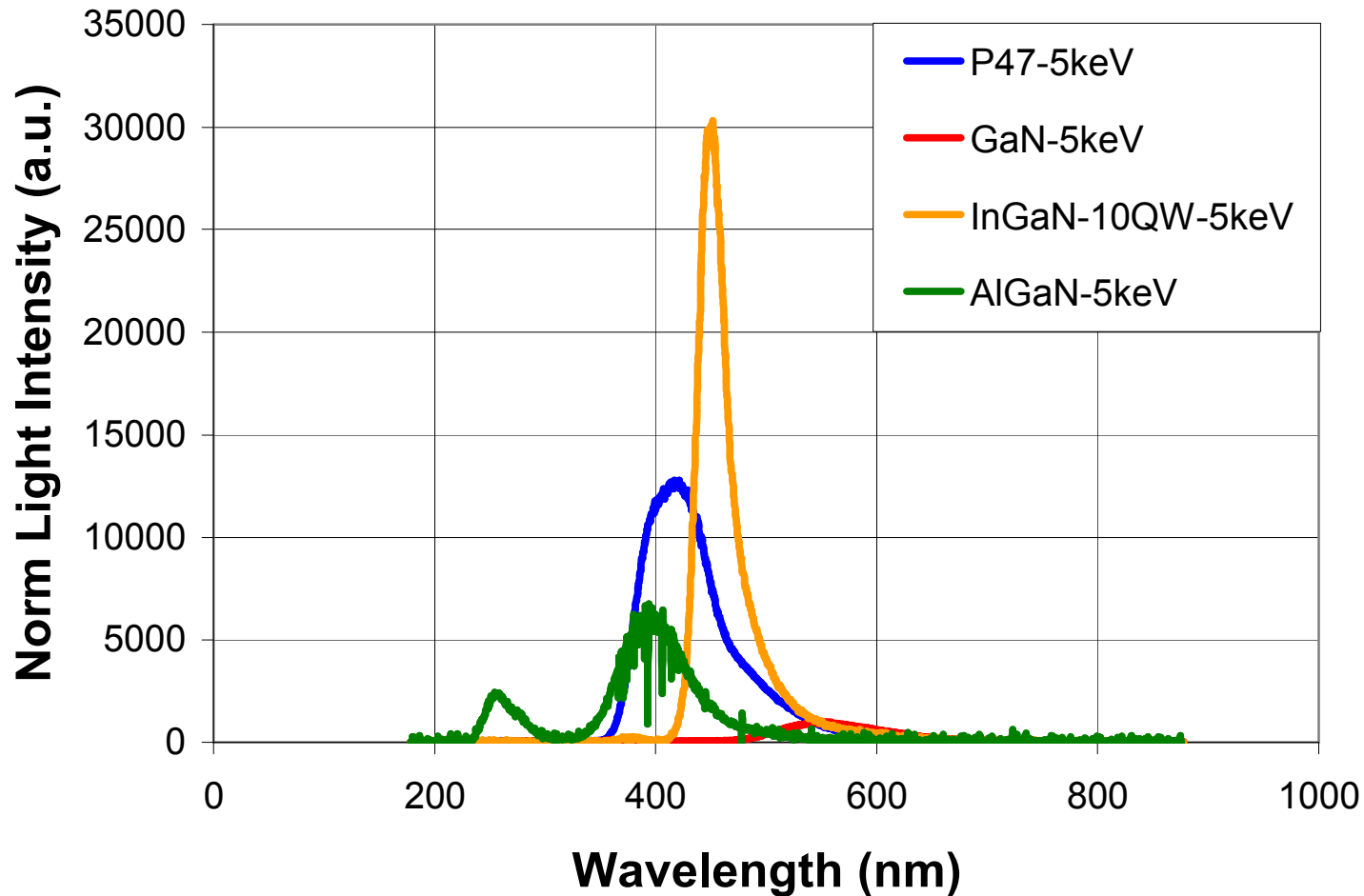
# Waveforms



$\tau(\text{GaN-}n=1 \times 10^{17}) \sim 200 \mu\text{s}$ ,  $\tau(\text{GaN-}n=5 \times 10^{17}) = 30 \mu\text{s}$ ,  $\tau(\text{P47}) \sim 50 \text{ ns}$ ,  $\tau(\text{Bicorn}) \sim 2 \text{ ns}$

# 5 keV electrons (Flat Panels) Cathode-Luminescence

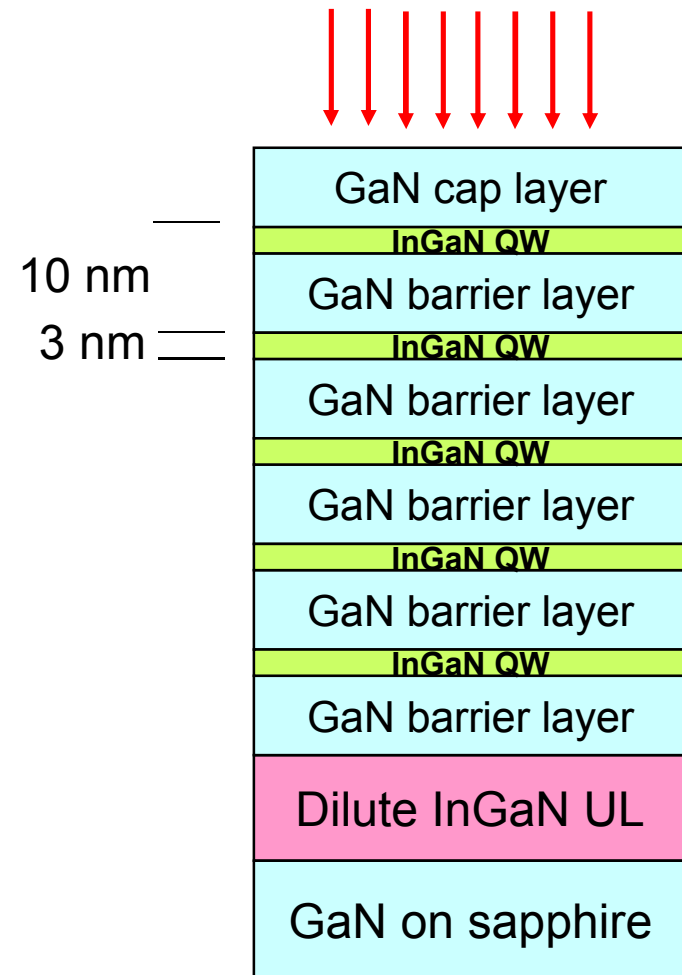
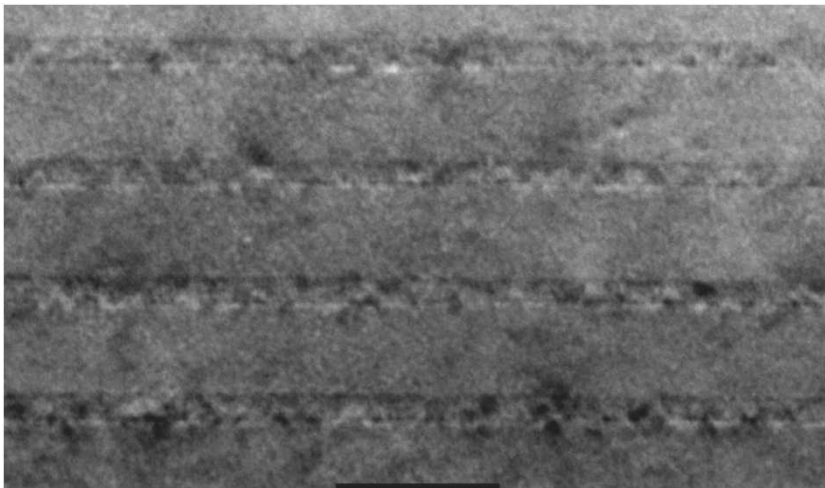
**CL Yield: P47=1, GaN=0.12, InGaN=1.11, AlGaN=0.51**



# InGaN Quantum Wells for electron detection

D. D. Koleske, S. R. Lee, A. J. Fischer, M. H. Crawford, D. M. Follstaedt, K. C. Cross, N. A. Missert and G. Thaler, Sandia National Laboratories

## Multi-wafer rotating-disk MOCVD



**Each of the MQW structures has:**

**Indium content =  $15.1 \pm 0.7$  %**

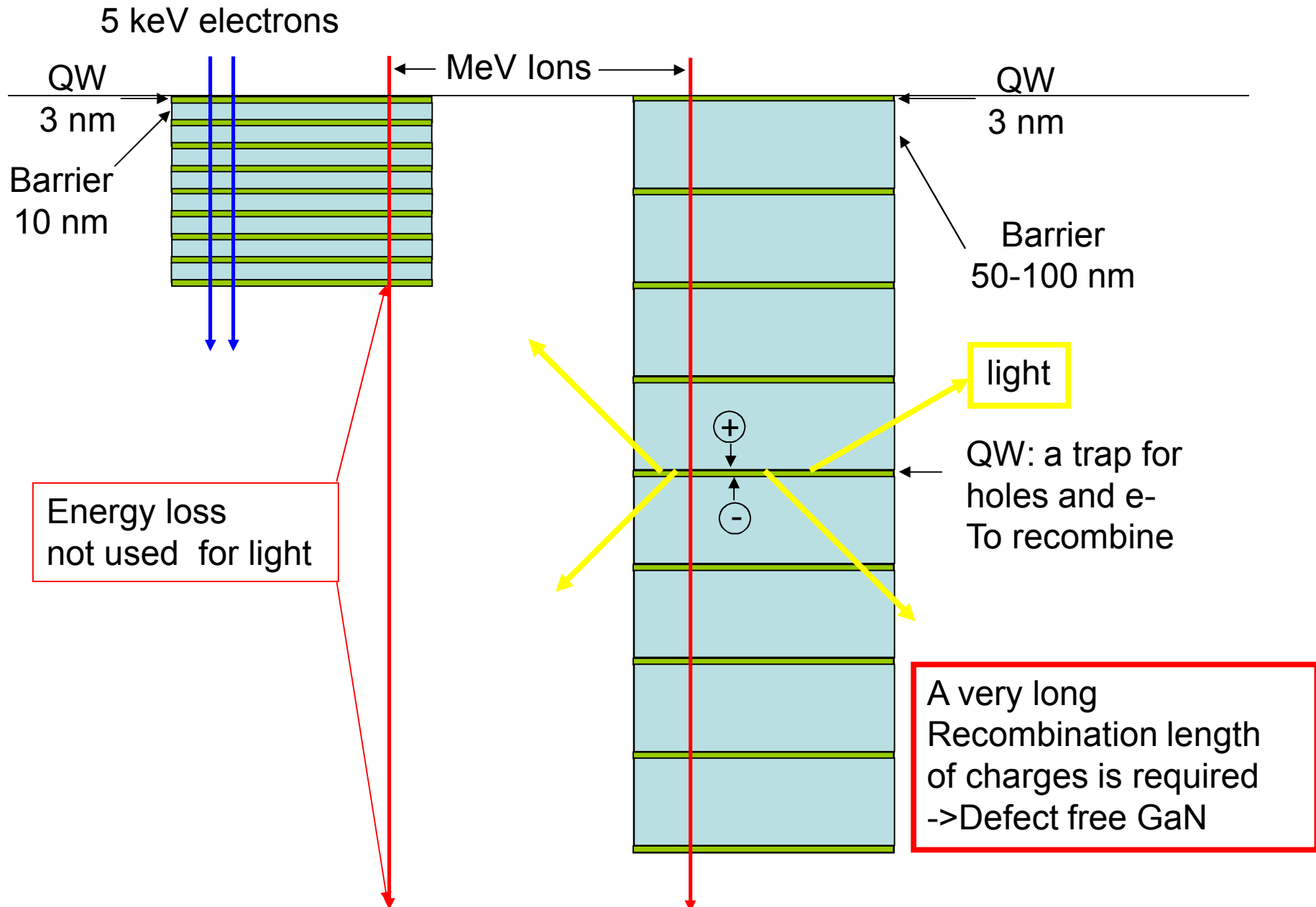
**QW thickness =  $26.3 \pm 3.4$  Å**

**Barrier thickness =  $94.6 \pm 6.2$  Å**

**UL indium content =  $1.4 \pm 0.3$  %**

**PL wavelength =  $457 \pm 6$  nm**

# Quantum Wells for Ions Detection: a project

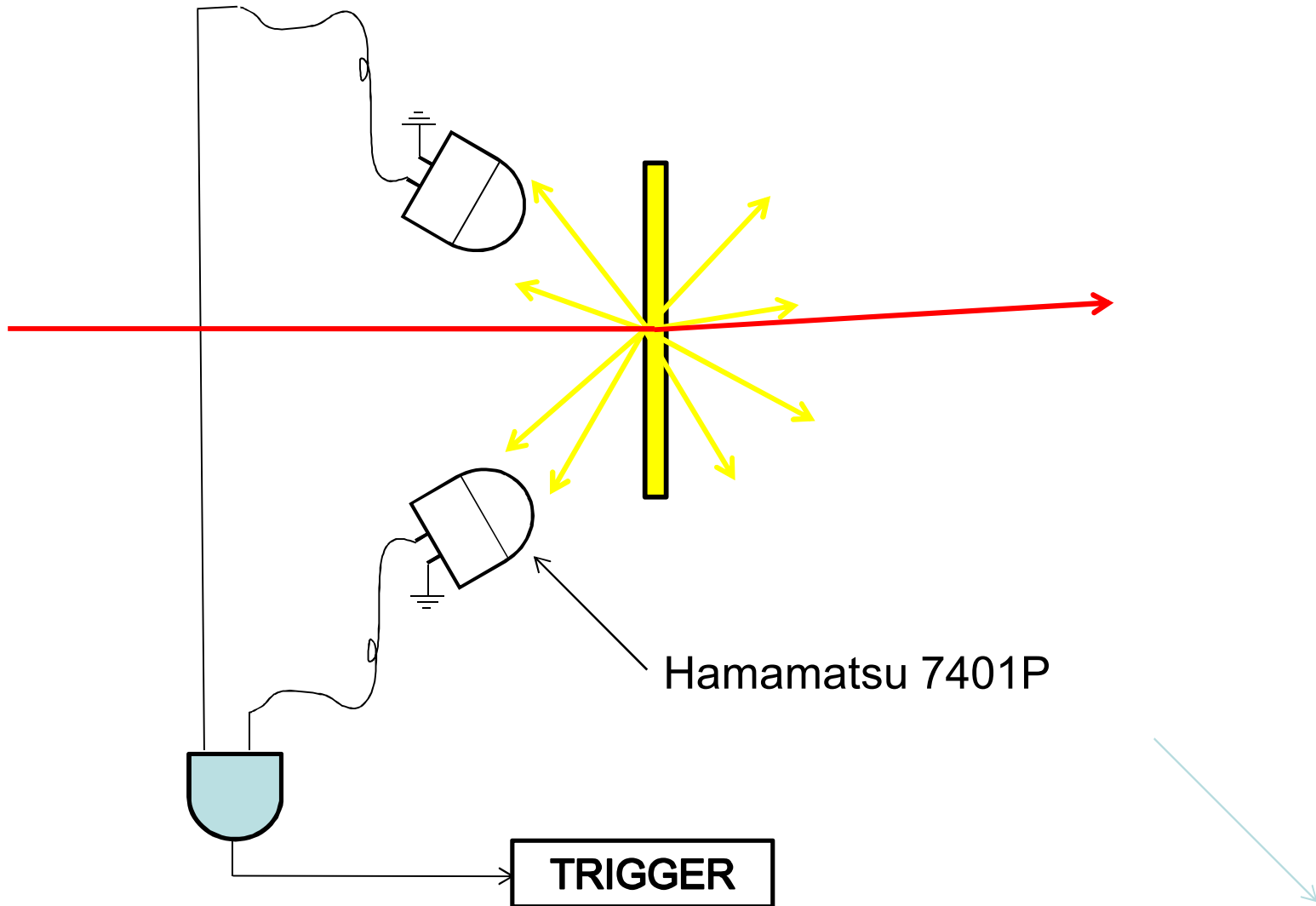




# Cyclotron IPEM Conclusion

**IPEM** may become the best tool  
for **MICROCHIPS SEE MAPPING**  
at **CYCLOTRON ENERGIES**  
for the next decade,  
provided its spatial resolution is suitably  
improved by employing efficient and “quick”  
phosphors

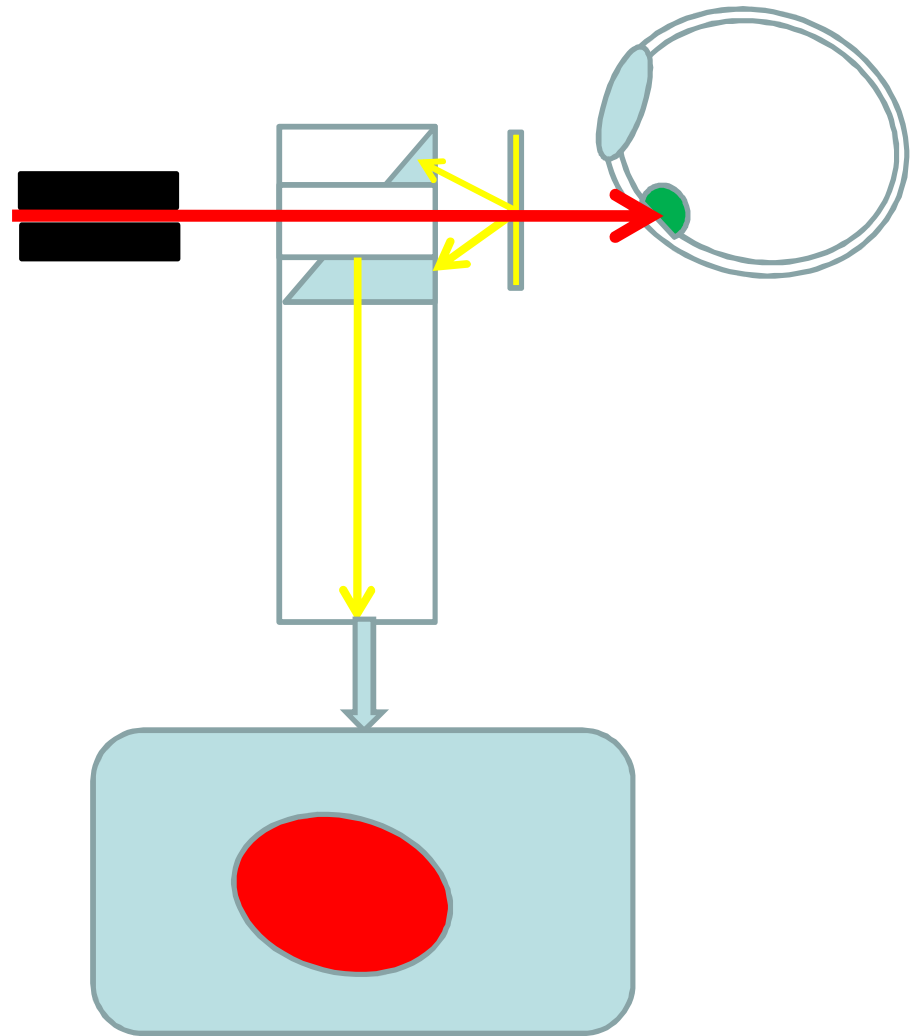
# Trigger



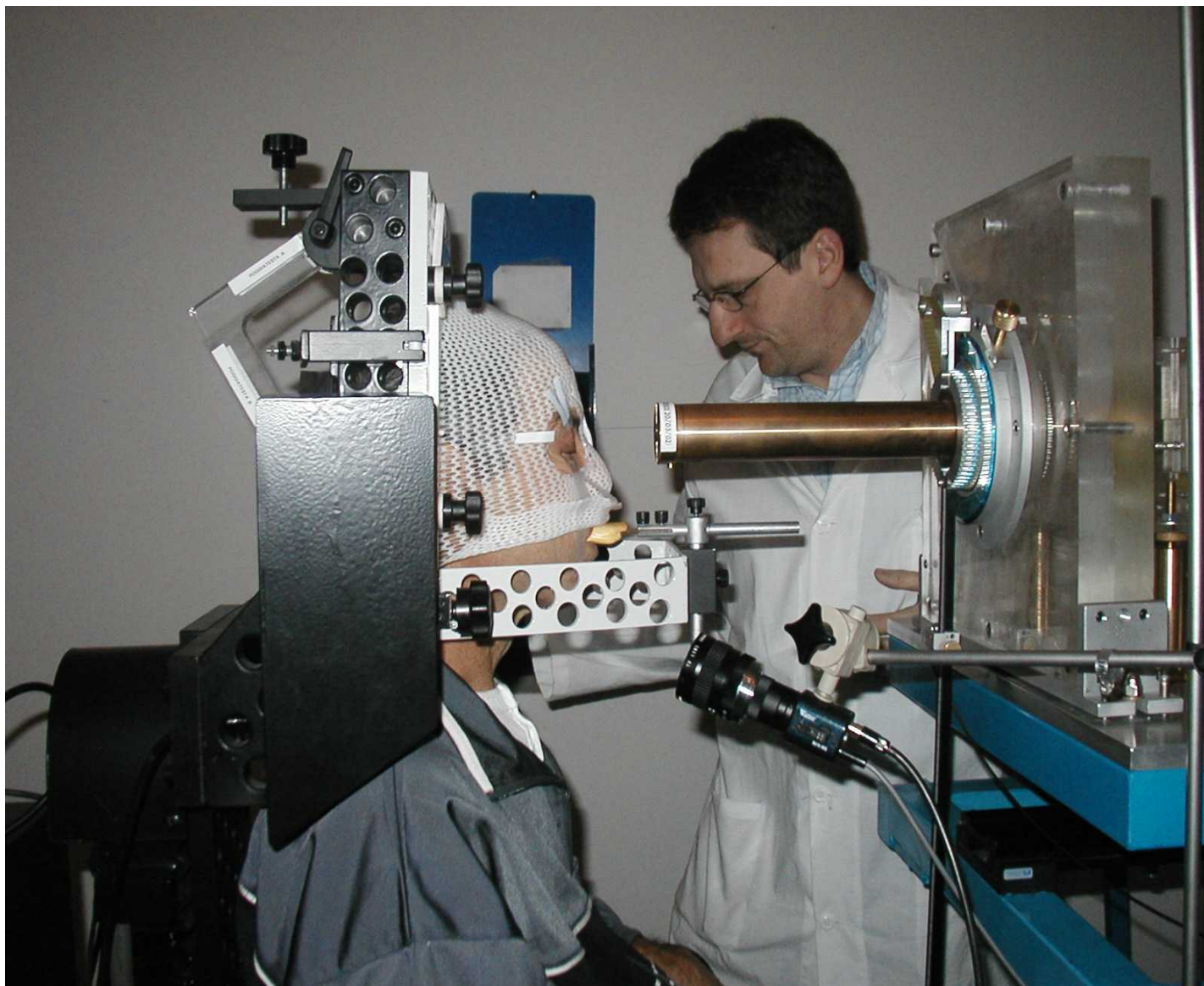
# Monitor

In the hadron radiotherapy of a small delicate area, like the eye in uveal and iris melanoma, one needs to accurately monitor the dose being delivered to any pixel of the field, instant by instant, to avoid damages to the patient.

In these applications a “continuous monitor” is required, and the detector should not stop or even degrade too much the beam.



## CATANA (Centro di Adroterapia e Applicazioni Nucleari Avanzate)



**HVALA LIJEPA**

**Thank you very much**

**Molte Grazie**